

# PESD5V0S2BT

Low capacitance bidirectional double ESD protection diode

Rev. 03 — 9 February 2009

Product data sheet

## 1. Product profile

### 1.1 General description

Low capacitance bidirectional double ElectroStatic Discharge (ESD) protection diode in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package designed to protect two data lines from the damage caused by ESD and other transients.

### 1.2 Features

- Bidirectional ESD protection of two lines
- Low diode capacitance
- Max. peak pulse power:  $P_{PP} = 130$  W at  $t_p = 8/20 \mu s$
- Low clamping voltage:  $V_{CL} = 14$  V at  $I_{PP} = 12$  A
- Ultra low leakage current:  $I_{RM} = 5$  nA at  $V_{RWM} = 5$  V
- ESD protection up to 30 kV
- IEC 61000-4-2; level 4 (ESD)
- IEC 61000-4-5 (surge);  $I_{PP} = 12$  A at  $t_p = 8/20 \mu s$

### 1.3 Applications

- Cellular handsets and accessories
- Portable electronics
- Computers and peripherals
- Communication systems
- Audio and video equipment

### 1.4 Quick reference data

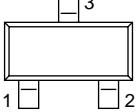
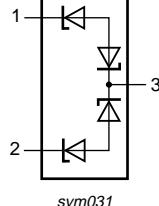
**Table 1. Quick reference data**

$T_{amb} = 25^\circ C$  unless otherwise specified.

| Symbol    | Parameter                | Conditions                  | Min | Typ | Max | Unit |
|-----------|--------------------------|-----------------------------|-----|-----|-----|------|
| $V_{RWM}$ | reverse standoff voltage |                             | -   | -   | 5   | V    |
| $C_d$     | diode capacitance        | $f = 1$ MHz;<br>$V_R = 0$ V | -   | 35  | 45  | pF   |

## 2. Pinning information

Table 2. Pinning

| Pin | Description    | Simplified outline   | Graphic symbol  |
|-----|----------------|--|---|
| 1   | cathode 1      |  |   |
| 2   | cathode 2      |  |   |
| 3   | double cathode |  |  |

## 3. Ordering information

Table 3. Ordering information

| Type number | Package |  | Version |
|-------------|---------|--|---------|
|             | Name    | Description                              |         |
| PESD5V0S2BT | -       | plastic surface-mounted package; 3 leads | SOT23   |

## 4. Marking

Table 4. Marking

| Type number | Marking code <sup>[1]</sup> |
|-------------|-----------------------------|
| PESD5V0S2BT | *G5                         |

[1] \* = -: made in Hong Kong  
 \* = p: made in Hong Kong  
 \* = t: made in Malaysia  
 \* = W: made in China

## 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol           | Parameter            | Conditions               | Min    | Max  | Unit  |
|------------------|----------------------|--------------------------|--------|------|-------|
| <b>Per diode</b> |                      |                          |        |      |       |
| P <sub>PP</sub>  | peak pulse power     | t <sub>p</sub> = 8/20 µs | [1][2] | -    | 130 W |
| I <sub>PP</sub>  | peak pulse current   | t <sub>p</sub> = 8/20 µs | [1][2] | -    | 12 A  |
| T <sub>j</sub>   | junction temperature |                          | -      | 150  | °C    |
| T <sub>amb</sub> | ambient temperature  |                          | -65    | +150 | °C    |
| T <sub>stg</sub> | storage temperature  |                          | -65    | +150 | °C    |

[1] Non-repetitive current pulse 8/20 µs exponential decay waveform.

[2] Measured from pin 1 to 3 or pin 2 to 3.

**Table 6. ESD maximum ratings**

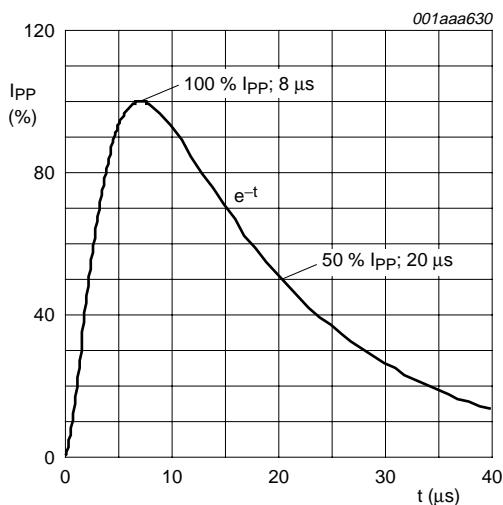
| Symbol    | Parameter                       | Conditions                        | Min    | Max | Unit  |
|-----------|---------------------------------|-----------------------------------|--------|-----|-------|
| $V_{ESD}$ | electrostatic discharge voltage | IEC 61000-4-2 (contact discharge) | [1][2] | -   | 30 kV |
|           |                                 | MIL-STD-883 (human body model)    | -      | 10  | kV    |

[1] Device stressed with ten non-repetitive ESD pulses.

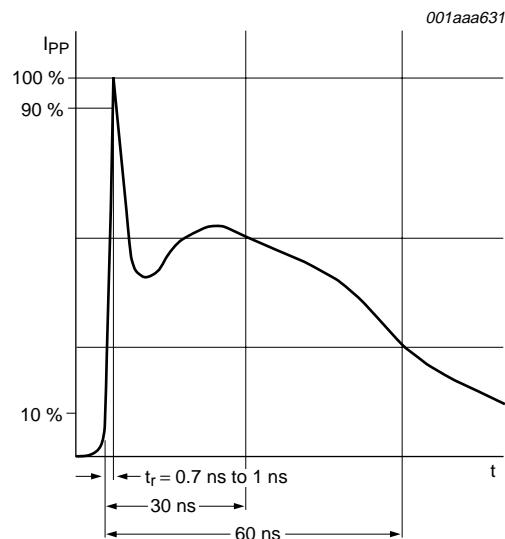
[2] Measured from pin 1 to 3 or pin 2 to 3.

**Table 7. ESD standards compliance**

| Standard                                | Conditions                      |
|---|---------------------------------|
| IEC 61000-4-2; level 4 (ESD)            | > 15 kV (air); > 8 kV (contact) |
| MIL-STD-883; class 3 (human body model) | > 4 kV                          |



**Fig 1. 8/20  $\mu$ s pulse waveform according to IEC 61000-4-5**



**Fig 2. ESD pulse waveform according to IEC 61000-4-2**

## 6. Characteristics

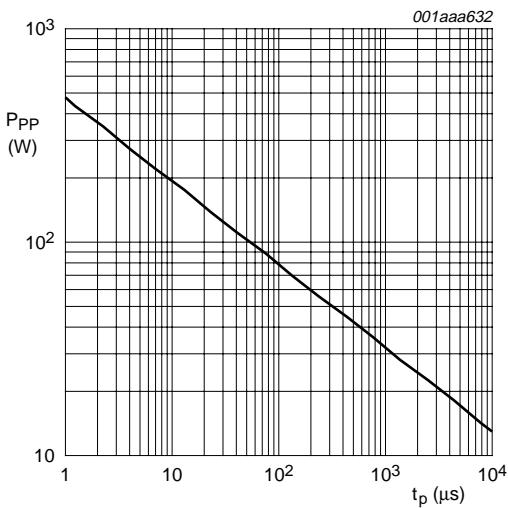
**Table 8. Electrical characteristics**

$T_{amb} = 25^\circ C$  unless otherwise specified.

| Symbol           | Parameter                | Conditions               | Min    | Typ | Max | Unit     |
|------------------|--------------------------|--------------------------|--------|-----|-----|----------|
| <b>Per diode</b> |                          |                          |        |     |     |          |
| $V_{RWM}$        | reverse standoff voltage |                          | -      | -   | 5   | V        |
| $I_{RM}$         | reverse leakage current  | $V_{RWM} = 5$ V          | -      | 5   | 100 | nA       |
| $V_{CL}$         | clamping voltage         | $I_{PP} = 1$ A           | [1][2] | -   | 10  | V        |
|                  |                          | $I_{PP} = 12$ A          | [1][2] | -   | 14  | V        |
| $V_{BR}$         | breakdown voltage        | $I_R = 1$ mA             | 5.5    | -   | 9.5 | V        |
| $r_{dif}$        | differential resistance  | $I_R = 1$ mA             | -      | -   | 50  | $\Omega$ |
| $C_d$            | diode capacitance        | $f = 1$ MHz; $V_R = 0$ V | -      | 35  | 45  | pF       |

[1] Non-repetitive current pulse 8/20  $\mu$ s exponential decay waveform.

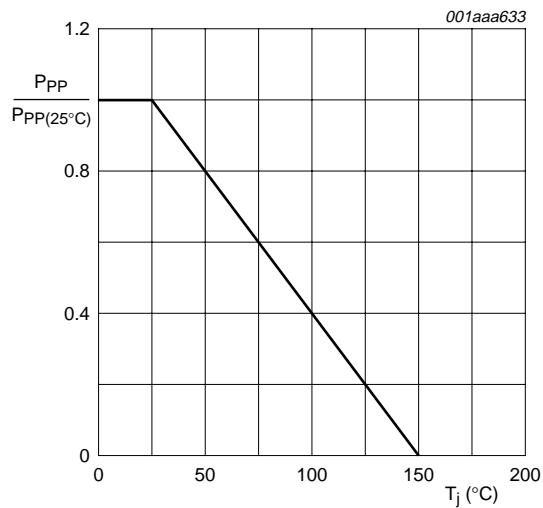
[2] Measured from pin 1 to 3 or pin 2 to 3.



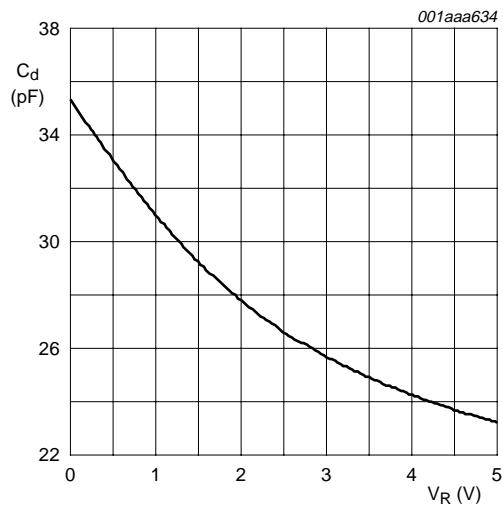
$T_{amb} = 25^\circ C$

$t_p = 8/20 \mu$ s exponential decay waveform

**Fig 3. Peak pulse power dissipation as a function of pulse duration; typical values**

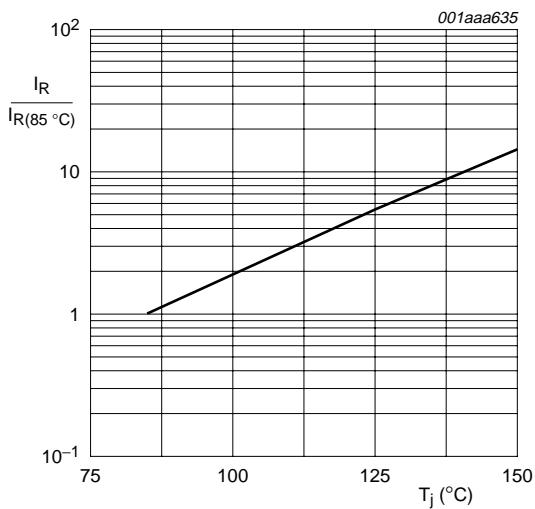


**Fig 4. Relative variation of peak pulse power as a function of junction temperature; typical values**



$T_{amb} = 25^{\circ}\text{C}$ ;  $f = 1 \text{ MHz}$

**Fig 5.** Diode capacitance as a function of reverse voltage; typical values



$I_R < 1 \text{ nA}$  measured at  $T_{amb} = 25^{\circ}\text{C}$

**Fig 6.** Relative variation of reverse current as a function of junction temperature; typical values

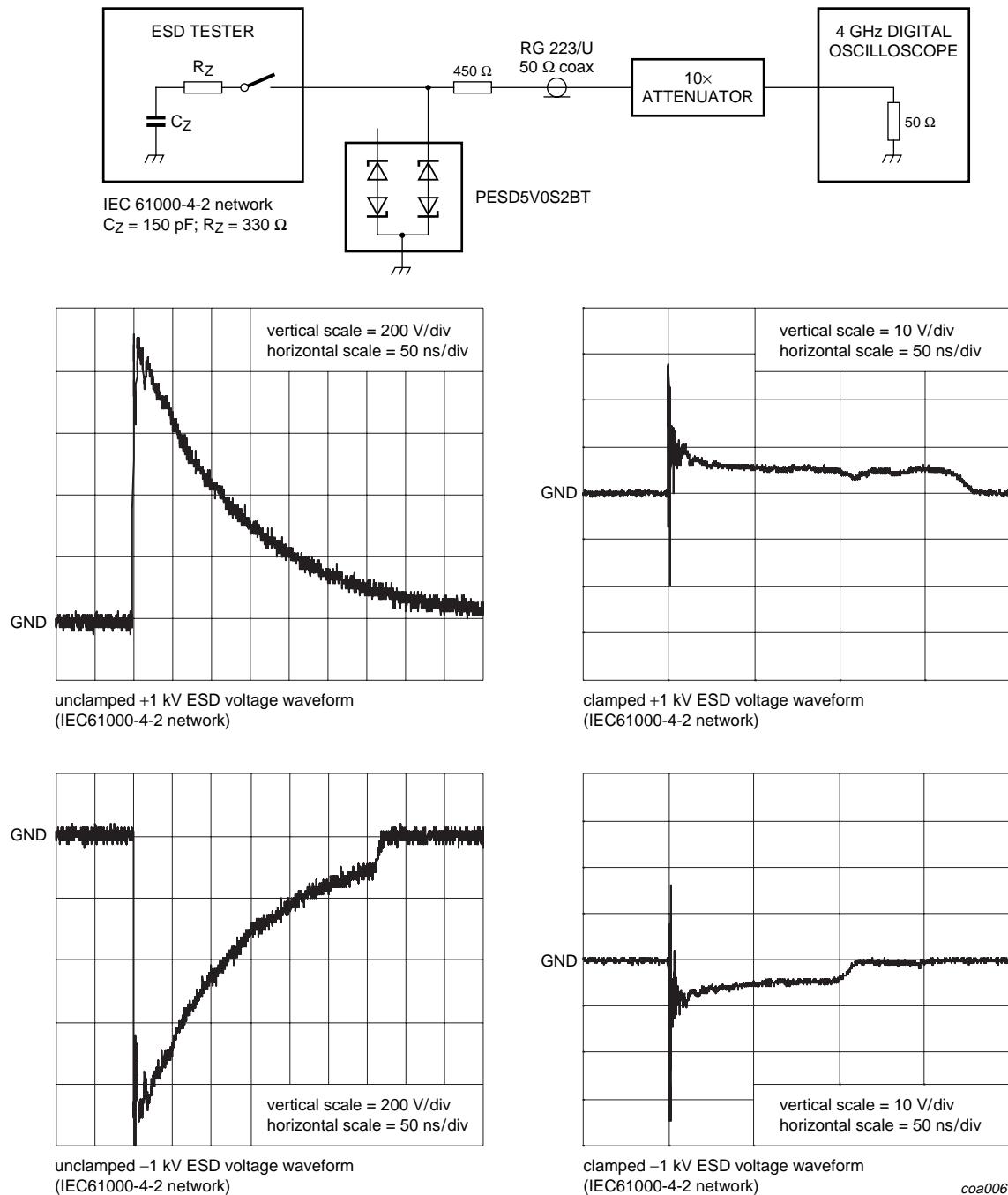
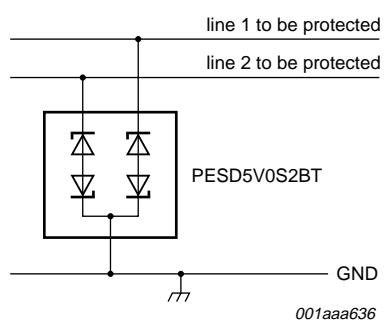


Fig 7. ESD clamping test setup and waveforms

## 7. Application information

The PESD5V0S2BT is designed for the bidirectional protection of two lines from the damage caused by ElectroStatic Discharge (ESD) and surge pulses.

The PESD5V0S2BT may be used on lines where the signal polarities are both, positive and negative with respect to ground. The PESD5V0S2BT provides a surge capability of 130 W per line for an 8/20  $\mu$ s waveform.



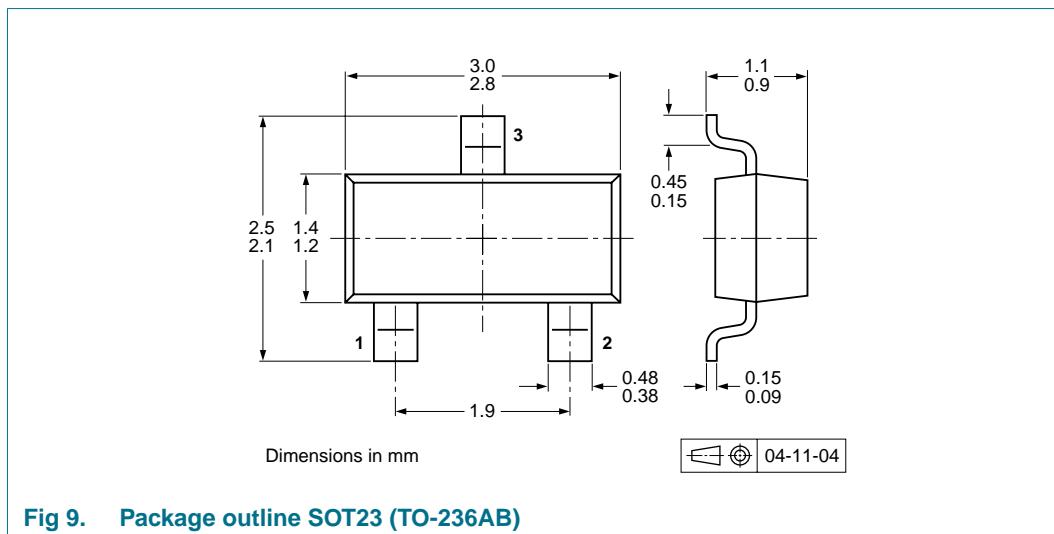
**Fig 8. Typical application for bidirectional protection of two lines**

### Circuit board layout and protection device placement:

Circuit board layout is critical for the suppression of ESD, Electrical Fast Transient (EFT) and surge transients. The following guidelines are recommended:

1. Place the PESD5V0S2BT as close to the input terminal or connector as possible.
2. The path length between the PESD5V0S2BT and the protected line should be minimized.
3. Keep parallel signal paths to a minimum.
4. Avoid running protected conductors in parallel with unprotected conductors.
5. Minimize all Printed-Circuit Board (PCB) conductive loops including power and ground loops.
6. Minimize the length of the transient return path to ground.
7. Avoid using shared transient return paths to a common ground point.
8. Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

## 8. Package outline



## 9. Packing information

**Table 9. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.[\[1\]](#)

| Type number | Package | Description                    | Packing quantity |       |
|-------------|---------|--------------------------------|------------------|-------|
|             |         |                                | 3000             | 10000 |
| PESD5V0S2BT | SOT23   | 4 mm pitch, 8 mm tape and reel | -215             | -235  |

[1] For further information and the availability of packing methods, see [Section 13](#).

## 10. Soldering

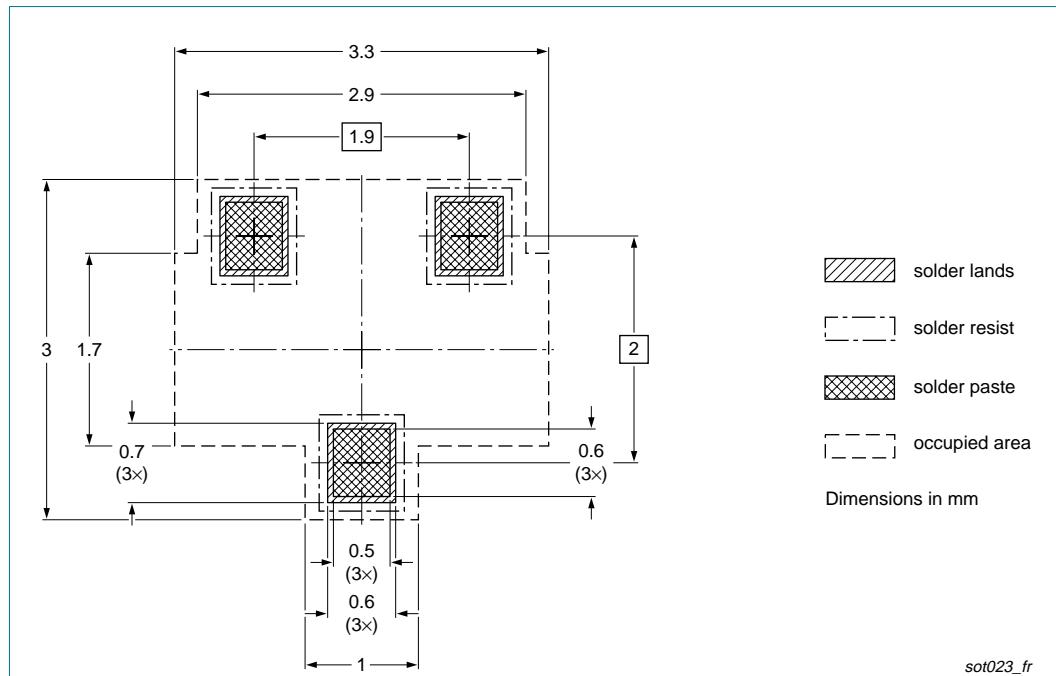


Fig 10. Reflow soldering footprint SOT23 (TO-236AB)

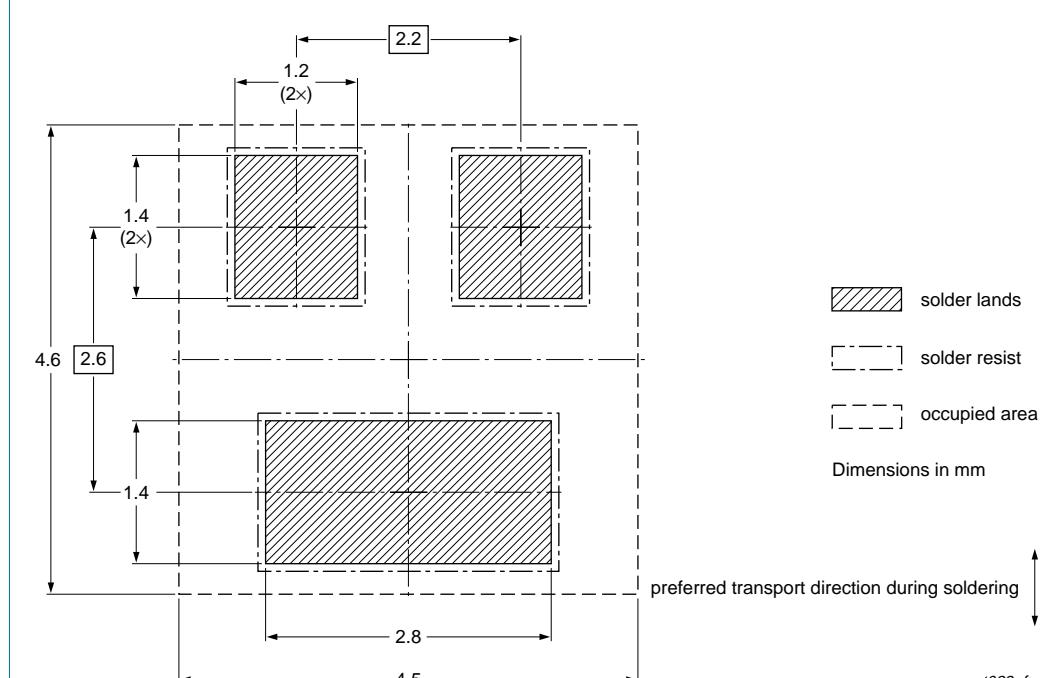


Fig 11. Wave soldering footprint SOT23 (TO-236AB)

## 11. Revision history

**Table 10. Revision history**

| Document ID    | Release date | Data sheet status  | Change notice | Supersedes    |
|----------------|--------------|--|---------------|---------------|
| PESD5V0S2BT_3  | 20090209     | Product data sheet   | -             | PESD5V0S2BT_2 |
| Modifications: |              | <ul style="list-style-type: none"><li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>Legal texts have been adapted to the new company name where appropriate.</li><li><a href="#">Table 6</a>: ESD electro static discharge capability redefined to <math>V_{ESD}</math> electrostatic discharge voltage</li><li><a href="#">Table 8</a>: <math>V_{(CL)R}</math> clamping voltage redefined to <math>V_{CL}</math></li><li><a href="#">Figure 4</a>: figure notes removed</li><li><a href="#">Section 7 "Application information"</a>: updated</li><li><a href="#">Figure 9</a>: superseded by minimized package outline drawing</li><li><a href="#">Section 9 "Packing information"</a>: added</li><li><a href="#">Section 10 "Soldering"</a>: added</li><li><a href="#">Section 12 "Legal information"</a>: updated</li></ul> |               |               |
| PESD5V0S2BT_2  | 20040527     | Product data sheet   | -             | PESD5V0S2BT_1 |
| PESD5V0S2BT_1  | 20040517     | Product data sheet   | -             | -             |

## 12. Legal information

### 12.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

### 12.2 Definitions

**Draft** — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

**Short data sheet** — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

### 12.3 Disclaimers

**General** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

**Suitability for use** — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental

damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

**Applications** — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

**Limiting values** — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

**Terms and conditions of sale** — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by NXP Semiconductors. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

**No offer to sell or license** — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

**Quick reference data** — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

### 12.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

## 13. Contact information

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

## 14. Contents

|           |                                |           |
|-----------|--------------------------------|-----------|
| <b>1</b>  | <b>Product profile</b>         | <b>1</b>  |
| 1.1       | General description            | 1         |
| 1.2       | Features                       | 1         |
| 1.3       | Applications                   | 1         |
| 1.4       | Quick reference data           | 1         |
| <b>2</b>  | <b>Pinning information</b>     | <b>2</b>  |
| <b>3</b>  | <b>Ordering information</b>    | <b>2</b>  |
| <b>4</b>  | <b>Marking</b>                 | <b>2</b>  |
| <b>5</b>  | <b>Limiting values</b>         | <b>2</b>  |
| <b>6</b>  | <b>Characteristics</b>         | <b>4</b>  |
| <b>7</b>  | <b>Application information</b> | <b>7</b>  |
| <b>8</b>  | <b>Package outline</b>         | <b>8</b>  |
| <b>9</b>  | <b>Packing information</b>     | <b>8</b>  |
| <b>10</b> | <b>Soldering</b>               | <b>9</b>  |
| <b>11</b> | <b>Revision history</b>        | <b>10</b> |
| <b>12</b> | <b>Legal information</b>       | <b>11</b> |
| 12.1      | Data sheet status              | 11        |
| 12.2      | Definitions                    | 11        |
| 12.3      | Disclaimers                    | 11        |
| 12.4      | Trademarks                     | 11        |
| <b>13</b> | <b>Contact information</b>     | <b>11</b> |
| <b>14</b> | <b>Contents</b>                | <b>12</b> |

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

founded by

**PHILIPS**

© NXP B.V. 2009.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

Date of release: 9 February 2009

Document identifier: PESD5V0S2BT\_3

# AMEYA360

## Components Supply Platform

### Authorized Distribution Brand :



### Website :

Welcome to visit [www.ameya360.com](http://www.ameya360.com)

### Contact Us :

#### ➤ Address :

401 Building No.5, JiuGe Business Center, Lane 2301, Yishan Rd  
Minhang District, Shanghai , China

#### ➤ Sales :

Direct +86 (21) 6401-6692  
Email amall@ameya360.com  
QQ 800077892  
Skype ameyasales1 ameyasales2

#### ➤ Customer Service :

Email service@ameya360.com

#### ➤ Partnership :

Tel +86 (21) 64016692-8333  
Email mkt@ameya360.com